Method for manufacturing encapsulated electronic components, particularly integrated circuits.

ABSTRACT

The invention relates to a method for manufacturing encapsulated electronic components (2), particularly integrated circuits, at least successively comprising the following steps: a) attaching electronic components (2) on a first side of an electrically conducting support (1) and electrically connecting (3) the electronic components to the electrically conducting support (1); b) using a mould to encapsulate the electronic components (2) with an encapsulating material (8) on just the first side of the electrically conducting support (1), while a second side of the support (1) is substantially completely shielded with the aid of an adhesive film; c) removing the adhesive film and separating, along cutting lines, the individual encapsulated electronic components (2), wherein bonding of the adhesive film to a second side to be shielded of the electrically conducting support (1) takes place between step a) and step b).

Fig. 4